

**DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**
**Product Summary**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$ $T_A = 25^\circ\text{C}$
24V	15m $\Omega$ @ $V_{GS} = 4.5\text{V}$	6.5A
	20m $\Omega$ @ $V_{GS} = 2.5\text{V}$	5.6A

**Description and Applications**

This new generation MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

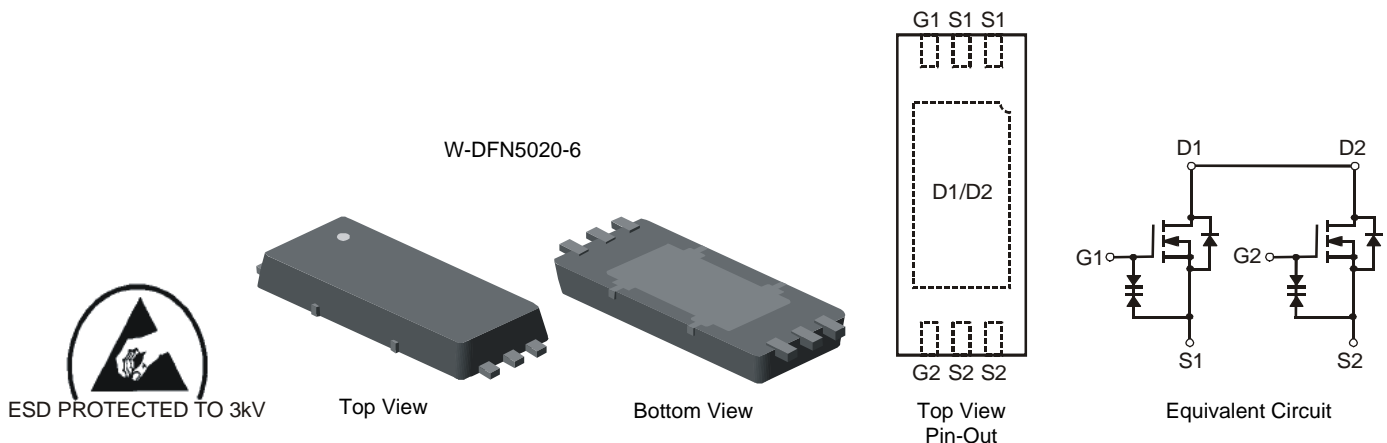
- DC-DC Converters
- Power management functions

**Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **ESD Protected up to 3kV**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: W-DFN5020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.03 grams (approximate)


**Ordering Information (Note 3)**

Part Number	Case	Packaging
DMG5802LFX-7	W-DFN5020-6	3000 / Tape & Reel

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
  3. For packaging details, go to our website at <http://www.diodes.com>.

**Marking Information**


ME = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: X = 2010)  
 M = Month (ex: 9 = September)

**Date Code Key**

Date Code Key

Year	2010	2011	2012	2013	2014	2015	2016
Code	X	Y	Z	A	B	C	D

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	24	V
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note 4) V <sub>GS</sub> = 4.5V	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	6.5	A
		T <sub>A</sub> = 70°C		5.2	
Continuous Drain Current (Note 4) V <sub>GS</sub> = 2.5V	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	5.6	A
		T <sub>A</sub> = 70°C		4.5	
Pulsed Drain Current (Note 5)			I <sub>DM</sub>	70	A

**Thermal Characteristics**

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 4)	P <sub>D</sub>	0.98	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = 25°C (Note 4)	R <sub>θJA</sub>	126.5	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise stated

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	24	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C	I <sub>DSS</sub>	-	-	1.0	μA	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.6	0.9	1.5	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	-	11	15	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.5A
		-	12	17		V <sub>GS</sub> = 4V, I <sub>D</sub> = 5.6A
		-	13	18		V <sub>GS</sub> = 3.1V, I <sub>D</sub> = 5.6A
		-	14	20		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 5.6A
Forward Transfer Admittance	Y <sub>fs</sub>	-	17	-	S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 6.5A
Diode Forward Voltage	V <sub>SD</sub>	-	0.6	0.9	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A
<b>DYNAMIC CHARACTERISTICS (Note 7)</b>						
Input Capacitance	C <sub>iss</sub>	-	1066.4	-	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	-	132.0	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	127.1	-		
Gate Resistance	R <sub>g</sub>	-	1.47	-	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge V <sub>GS</sub> = 4.5V	Q <sub>g</sub>	-	14.5	-	nC	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 5.8A
Total Gate Charge V <sub>GS</sub> = 10V	Q <sub>q</sub>	-	31.3	-		
Gate-Source Charge	Q <sub>gs</sub>	-	2.0	-		
Gate-Drain Charge	Q <sub>gd</sub>	-	3.1	-		
Turn-On Delay Time	t <sub>D(on)</sub>	-	3.69	-	ns	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, R <sub>L</sub> = 2.1Ω, R <sub>G</sub> = 3Ω
Turn-On Rise Time	t <sub>r</sub>	-	13.43	-	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	32.18	-	ns	
Turn-Off Fall Time	t <sub>f</sub>	-	22.45	-	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
  - Repetitive rating, pulse width limited by junction temperature.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.

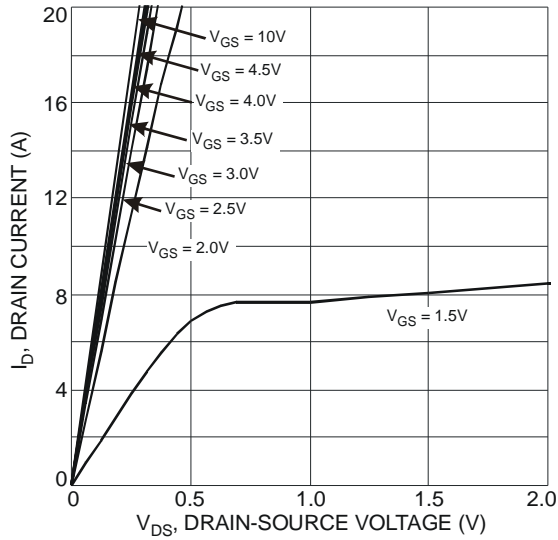


Fig. 1 Typical Output Characteristic

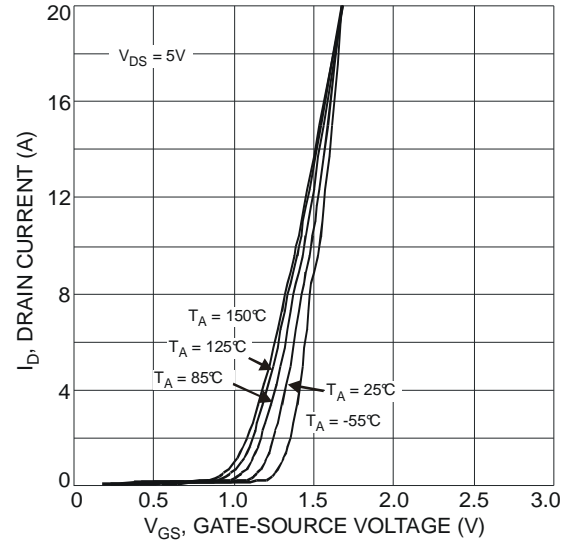


Fig. 2 Typical Transfer Characteristic

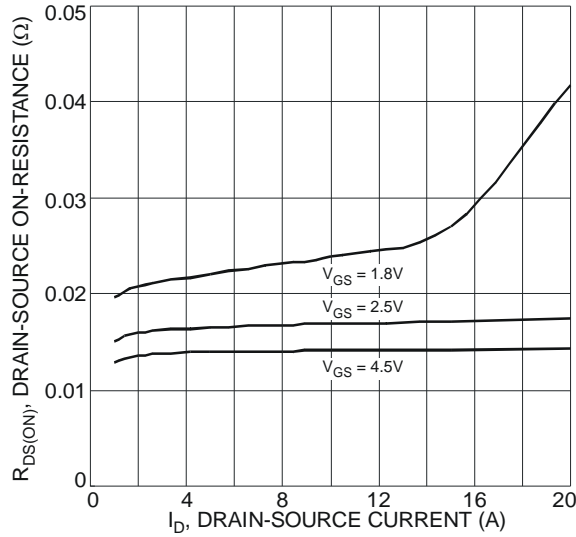


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

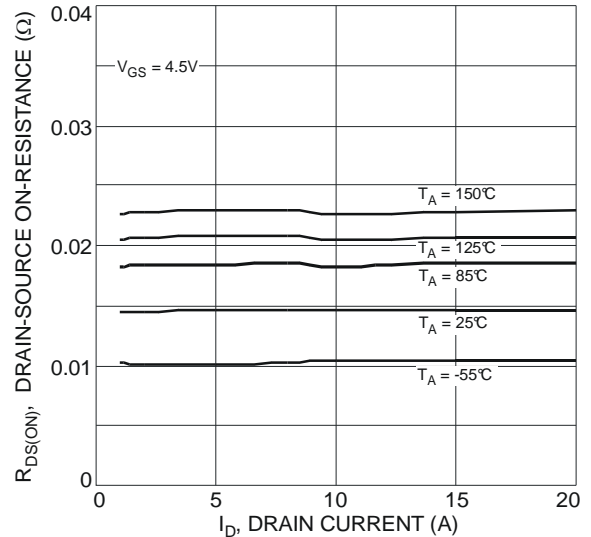


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

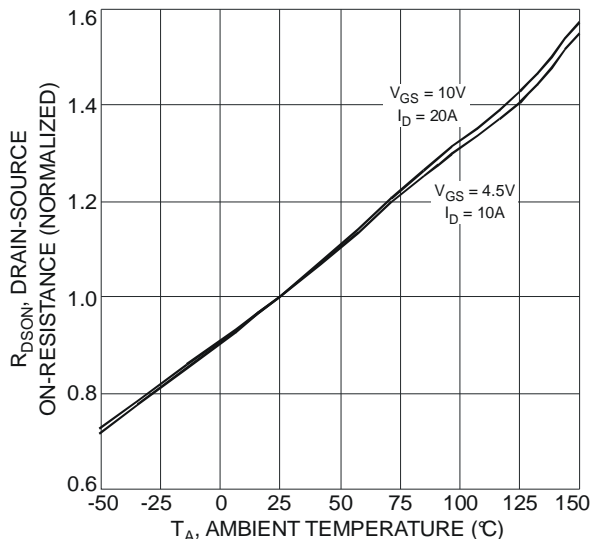


Fig. 5 On-Resistance Variation with Temperature

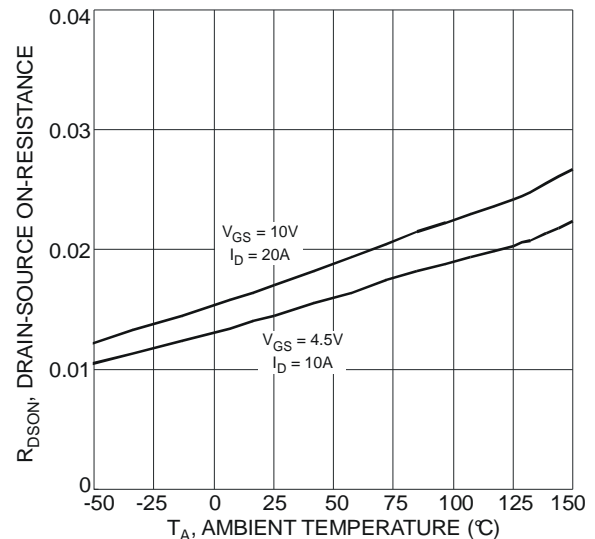


Fig. 6 On-Resistance Variation with Temperature

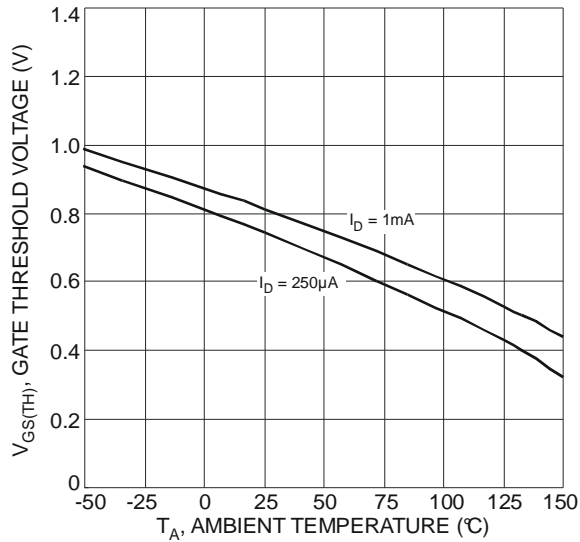


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

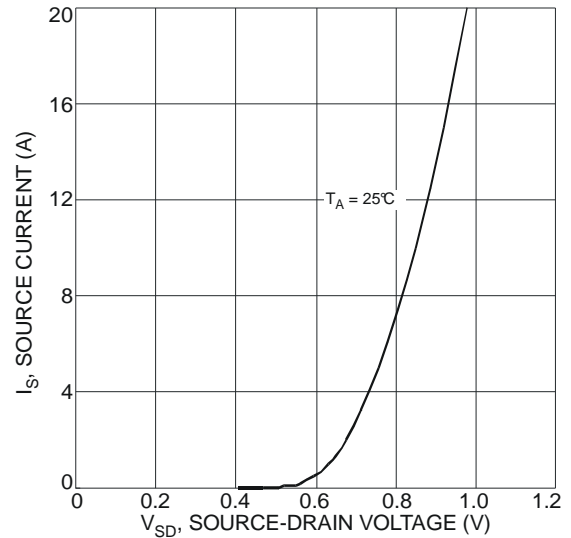


Fig. 8 Diode Forward Voltage vs. Current

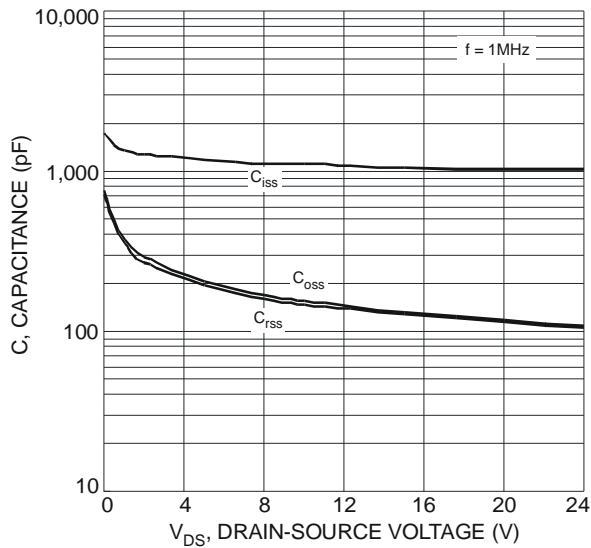


Fig. 9 Typical Total Capacitance

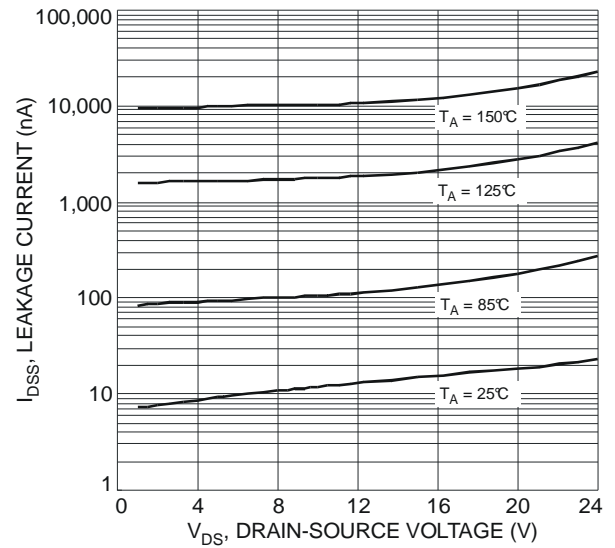


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

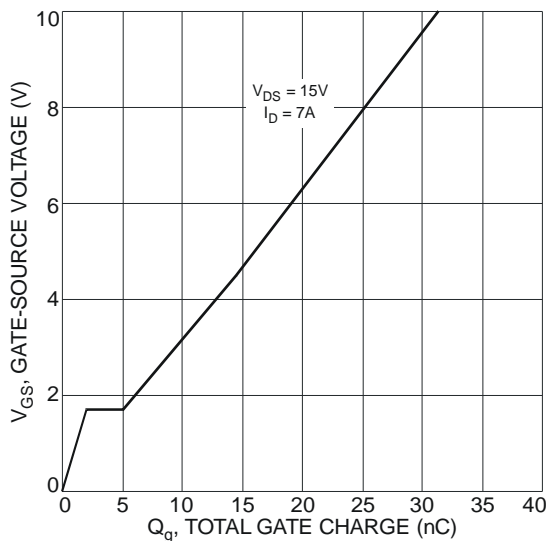


Fig. 11 Gate-Charge Characteristics

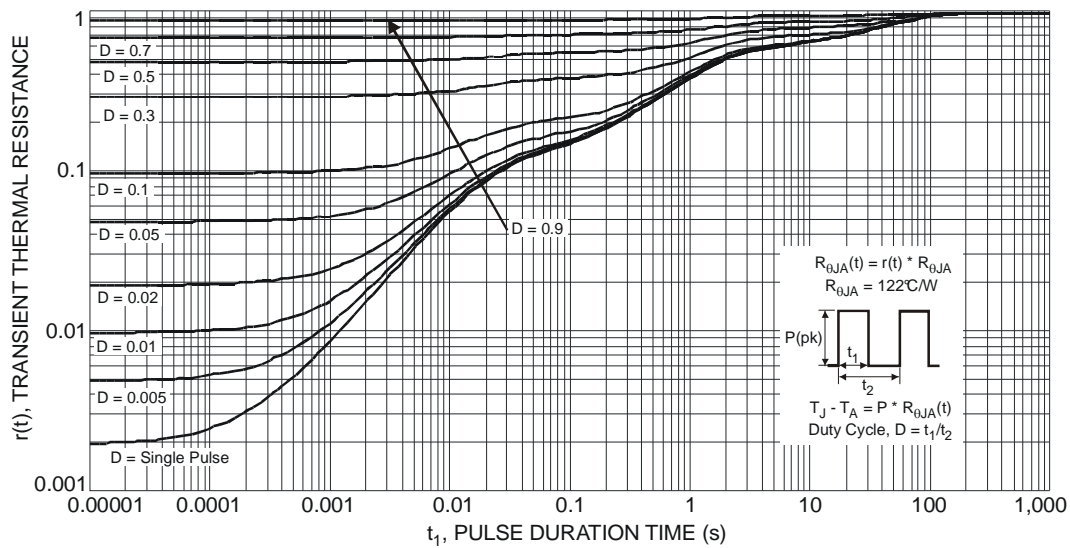
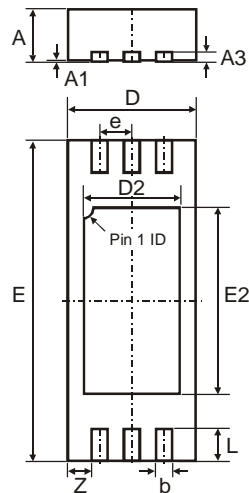


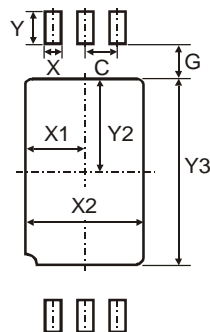
Fig. 12 Transient Thermal Response

## Package Outline Dimensions



W-DFN5020-6			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	—	—	0.15
b	0.20	0.30	0.25
D	1.90	2.10	2.00
D2	1.40	1.60	1.50
e	—	—	0.50
E	4.90	5.10	5.00
E2	2.80	3.00	2.90
L	0.35	0.65	0.50
Z	—	—	0.375
All Dimensions in mm			

## Suggested Pad Layout



Dimensions	Value (in mm)
C	0.50
G	0.35
X	0.35
X1	0.90
X2	1.80
Y	0.70
Y2	1.60
Y3	3.20

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